October 21 (Wed.), 2026

[Oral 06] CMP for Advanced Packaging / 3D Integration (II)

09:45-11:10

International Conference Hall (B1F)

● Session Chair: Takashi Watanabe (KIOXIA Corp., Japan)

09:45-10:10 [Oral 06-1]	**[Invited]** Considerations for Implementing CMP in Panel-Level Packaging Haedo Jeong, Heondeok Seo, Minjong Yuh, and Eunho Lee (G&P Tech., Korea)
10:10-10:30 [Oral 06-2]	Die-to-Wafer CMP: Overcoming Millimetric Planarization Challenges Driven by Die Density Julian Sturm (Univ. Grenoble Alpes, France), Valentin Callier (EBARA Precision Machinery Europe GmbH – Branch Office France, France), Clément Castan (Univ. Grenoble Alpes, France), Lucie Safourcade (EBARA Precision Machinery Europe GmbH – Branch Office France, France), Cécile Candegabe, Stella-Audrey Yamgouet Njouom, and Catherine Euvrard (Univ. Grenoble Alpes, France)
10:30-10:50 [Oral 06-3]	Effect of Slurry pH and Chelating Agent on Surface Roughness and Removal Rate of AlN in SiO_2 Slurry CMP Bo-Hyeok Cho, Jae-Ik Lee, Seung-Mahn Lee, and Jae-Dong Lee (KCTech, Korea)
10:50-11:10 [Oral 06-4]	Polishing Material Impact on Silicon Wafer Processing Hui Wang (Zhonghuan Advanced Semiconductor Materials Co., Ltd., China)